



US 20240237193A1

(19) **United States**

(12) **Patent Application Publication**  
**HUANG et al.**

(10) **Pub. No.: US 2024/0237193 A1**

(43) **Pub. Date: Jul. 11, 2024**

(54) **DUAL IN-LINE MEMORY MODULE (DIMM)  
SOLUTION THAT INCLUDES FLEXIBLE  
TRANSMISSION LINES**

(52) **U.S. Cl.**

CPC ..... **H05K 1/0253** (2013.01); **H05K 1/117**  
(2013.01); **H05K 1/141** (2013.01); **H05K**  
**2201/10189** (2013.01)

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**ABSTRACT**

An apparatus is described. The apparatus includes a memory module. The memory module includes a first printed circuit board having a first transmission line. The first printed circuit board has memory chips disposed thereon. The memory module includes a second printed board having a second transmission line that is coupled to the first transmission line to form a signal path through the first and second printed circuit boards. The second printed circuit board has greater flexibility than the first printed circuit board. The memory module includes a connector to align an I/O that is coupled to the second transmission line with a corresponding I/O that is associated with a motherboard that is to send and/or receive a signal to and/or from the signal path.

(21) Appl. No.: **18/618,075**

(22) Filed: **Mar. 27, 2024**

(30) **Foreign Application Priority Data**

Mar. 8, 2024 (WO) ..... PCT/CN2024/080740

**Publication Classification**

(51) **Int. Cl.**

**H05K 1/02** (2006.01)  
**H05K 1/11** (2006.01)  
**H05K 1/14** (2006.01)

